Table 1. PIN DESCRIPTION

Pin #	Pin Name	Type	Description
1	VSS	Power	Ground connection.
2	CLKIN	Input	LVCMOS External reference clock input.
3	ModOUT	Output	Spread Spectrum Clock Output.
4	VDD	Power	Power supply for the entire chip

Table 2. OPERATING CONDITIONS

Symbol	Description	Min	Max	Unit
V_{DD} (1.8 V)	Supply Voltage with respect to V_{SS}	1.6	2.0	V
V_{DD} (2.5 V/3.3 V)		2.3	3.6	
T_A	Operating temperature	−20	+85	°C
C_L	Load Capacitance		15	pF
C_{IN}	Input Capacitance		5	pF

Table 3. ABSOLUTE MAXIMUM RATING

Symbol	Description	Rating	Unit
V_{DD}, V_{IN}	Voltage on any input pin with respect to V_{SS}	−0.5 to +4.6	V
T_{STG}	Storage temperature	−65 to +125	°C
T_s	Max. Soldering Temperature (10 sec)	260	°C
T_J	Junction Temperature	150	°C
T_{DV}	Static Discharge Voltage (As per JEDEC STD22− A114−B)	2	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. DC Electrical Characteristics V_{DD} = 1.6 V – 2.0 V, T_A= –20°C to +85°C

Symbol	Parameter		Min	Typ	Max	Unit
V_{DD}	Supply Voltage with respect to VSS		1.6	1.8	2.0	V
I_{DD}	Dynamic supply current (Unloaded Output)	15MHz		1.3	1.8	mA
		30MHz		2	2.8	
I_{CC}	Static supply current (No Clock @ CLKIN)				1	μA
V_{IH}	Input high voltage		0.65*VDD			V
V_{IL}	Input low voltage				0.3*VDD	V
I_{IH}	Input high current (CLKIN pin)				10	μA
I_{IL}	Input low current (CLKIN pin)				10	μA
V_{OH}	Output high voltage, I_{OH} = – 8mA		0.75*VDD			V
V_{OL}	Output low voltage , I_{OL} = 8mA				0.2*VDD	V
Z_{OUT}	Output impedance			28		Ω

Table 5. AC ELECTRICAL CHARACTERISTICS V_{DD} = 1.6 V – 2.0 V, T_A = –20°C to +85°C

Symbol	Parameter		Min	Typ	Max	Unit
CLKIN	Input Clock frequency		15		30	MHz
ModOUT	Output Clock frequency		15		30	MHz
t_{LH} (Notes 1 and 2)	Output rise time (Measured between 20% to 80%)			1.7	2.7	nS
t_{HL} (Notes 1 and 2)	Output fall time (Measured between 80% to 20%)			1.4	2.4	nS
t_{JC} (Notes 2)	Cycle–to–cycle Jitter, Peak (1000 cycles)	15 MHz		400		pS
		24 MHz		250		
		30 MHz				
t_D (Notes 1 and 2)	Output duty cycle (Measured @ 50%)		45	50	55	%
t_{ON} (Notes 1 and 2)	PLL lock Time (Stable power supply, valid clock presented on CLKIN)				3	mS
fd	Frequency Deviation @ 24 MHz			±1.4	±1.55	%

1. All parameters are specified with 15 pF loaded output.
2. Parameter is guaranteed by design and characterization. Not 100% tested in production

Table 6. DC ELECTRICAL CHARACTERISTICS V_{DD} = 2.3 V – 3.6 V, T_A = –20°C to +85°C

Symbol	Parameter		Min	Typ	Max	Unit
V_{DD}	Supply Voltage with respect to VSS		2.3	2.8	3.6	V
I_{DD}	Dynamic supply current (Unloaded Output)	15MHz		1.7	3	mA
		30MHz		2.8	5	
		60MHz		5	9	
I_{CC}	Static supply current (No Clock @ CLKIN)				2	μA
V_{IH}	Input high voltage		0.65 * V_{DD}			V
V_{IL}	Input low voltage				0.3 * V_{DD}	V
I_{IH}	Input high current (CLKIN pin)				10	μA
I_{IL}	Input low current (CLKIN pin)				10	μA
V_{OH}	Output high voltage, I_{OH} = –16 mA		0.75 * V_{DD}			V
V_{OL}	Output low voltage, I_{OL} = 16 mA				0.2 * V_{DD}	V
Z_{OUT}	Output impedance			20		Ω

Table 7. AC ELECTRICAL CHARACTERISTICS V_{DD} = 2.3 V – 3.6 V, T_A = –20°C to +85°C

Symbol	Parameter		Min	Typ	Max	Unit
CLKIN	Input Clock frequency		15		60	MHz
ModOUT	Output Clock frequency		15		60	MHz
t_{LH} (Notes 3 and 4)	Output rise time (Measured between 20% to 80%)			0.8	1.6	nS
t_{HL} (Notes 3 and 4)	Output fall time (Measured between 80% to 20%)			0.8	1.6	nS
t_{JC} (Notes 4)	Cycle–to–cycle Jitter, Peak (1000 cycles)	15 MHz		350		pS
		24 MHz		250		
		60 MHz		100		
t_D (Notes 3 and 4)	Output duty cycle		45	50	55	%
t_{ON} (Notes 3 and 4)	PLL lock Time (Stable power supply, valid clock presented on CLKIN)				3	mS
fd	Frequency Deviation @ 24 MHz			±1.4	±1.55	%

3. All parameters are specified with 15 pF loaded output.
4. Parameter is guaranteed by design and characterization. Not 100% tested in production

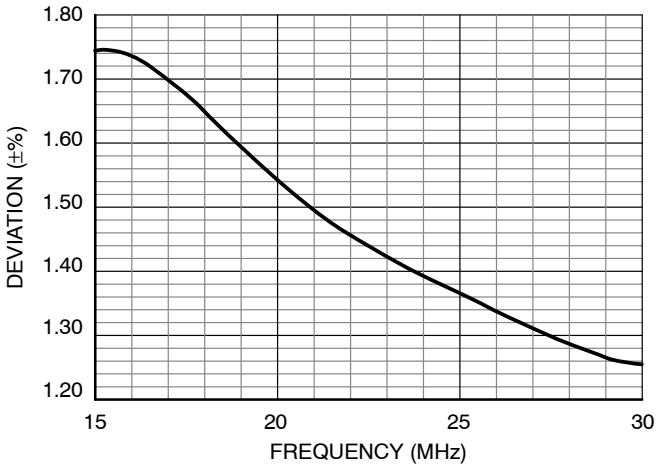


Figure 2. Deviation vs. Frequency (V_{DD} = 1.6 V – 2.0 V)

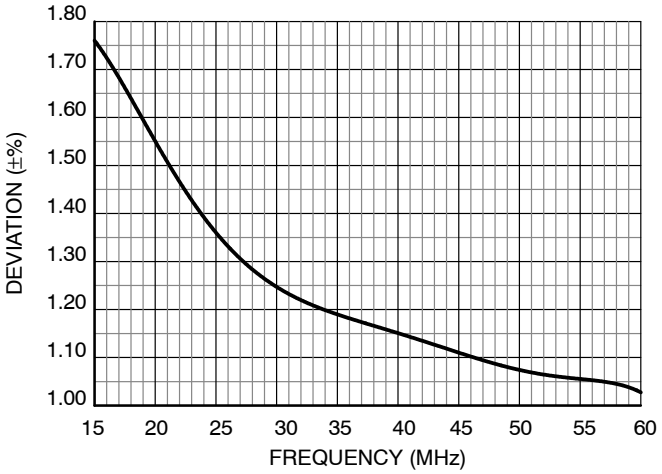
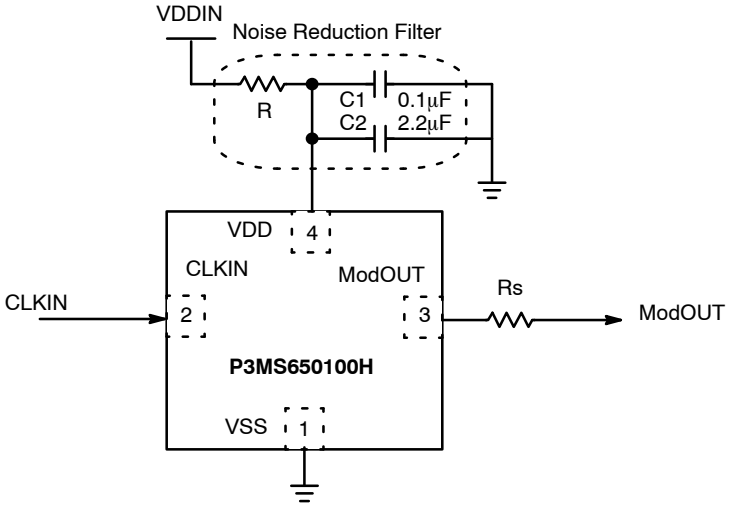


Figure 3. Deviation vs. Frequency (V_{DD} = 2.3 V – 3.6 V)



Rs = Trace Impedance of PCB – Output Impedance of Device (Z0)
Note: Refer Pin Description table for Functionality details

Figure 4. Typical Application Schematic

PCB Layout Recommendation

For optimum device performance, following guidelines are recommended.

- Dedicated V_{DD} and GND planes.
- The device must be isolated from system power supply noise. A 0.1μF and a 2.2 μF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between the decoupling capacitor and VDD pin. The PCB trace to VDD pin and the ground via should be kept as short as possible. All the VDD pins should have decoupling capacitors.
- In an optimum layout all components are on the same side of the board, minimizing vias through other signal layers.

A typical layout is shown in the figure below.

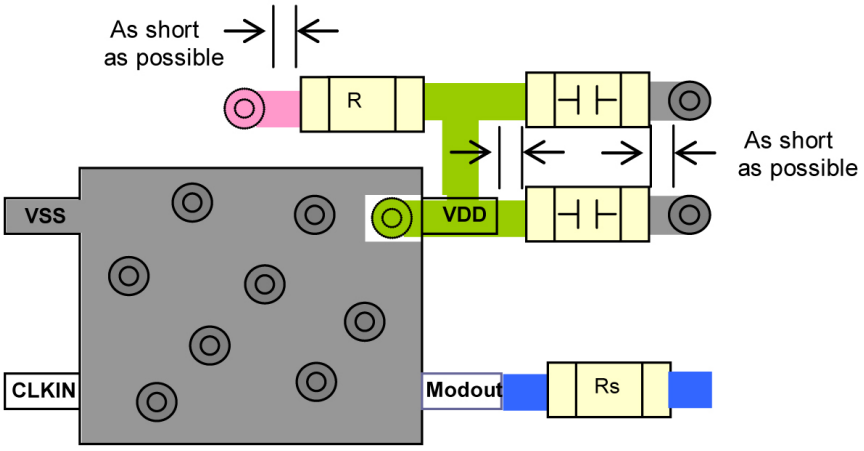


Figure 5. Recommended PCB Layout

ORDERING INFORMATION

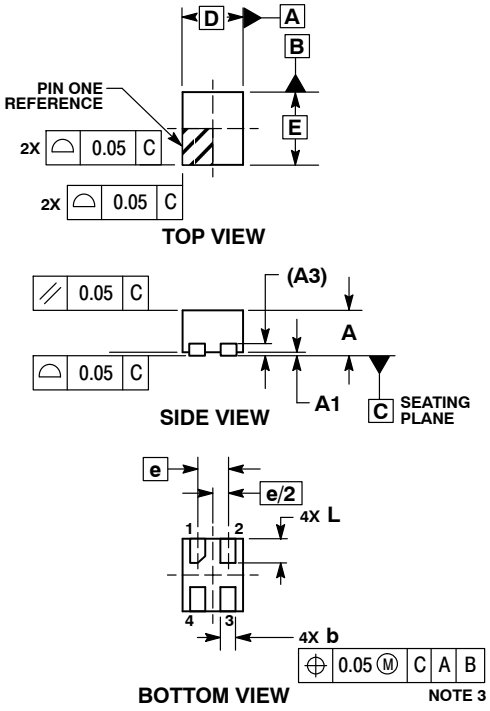
Ordering Code	Marking	Temperature	Package Type	Shipping†
P3MS650100H−4CR	A	−20°C to +85°C	4−pin (1.2 mm x 1.0 mm) WDFN (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*A “microdot” placed at the end of last row of marking or just below the last row toward the center of package indicates Pb−Free.

P3MS650100H

PACKAGE DIMENSIONS

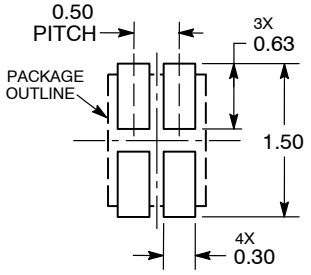
WDFN4, 1.0x1.2, 0.5P
CASE 511BS−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS	
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	1.00 BSC	
E	1.20 BSC	
e	0.50 BSC	
L	0.35	0.45

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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